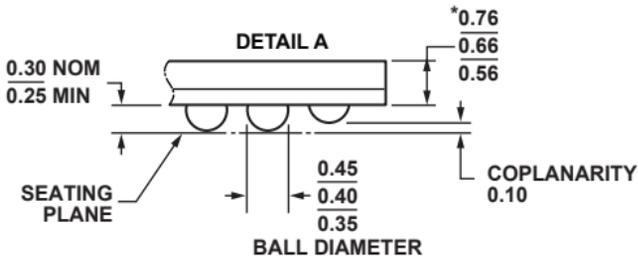
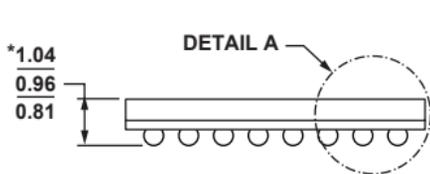
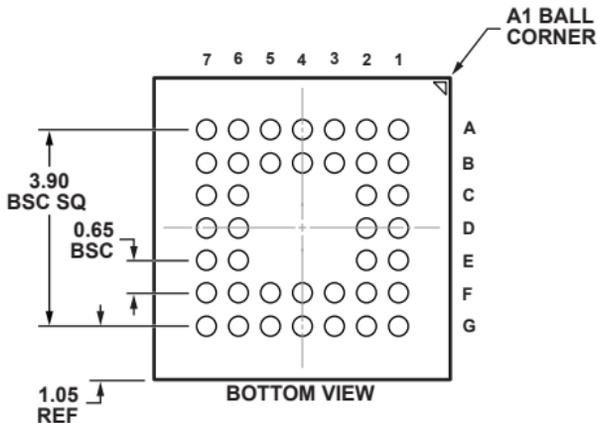
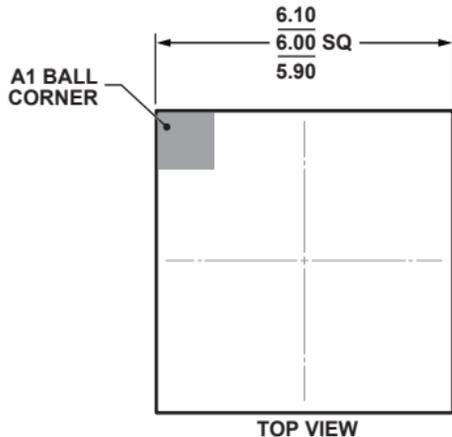


40-Ball Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-40-1)

Dimensions shown in millimeters



*COMPLIANT TO JEDEC STANDARDS MO-225 WITH THE EXCEPTION OF PACKAGE HEIGHT AND THICKNESS.